



ALL DIMENSIONS ARE SYMMETRIC ABOUT THE CENTERLINE.
(COMPONENT SIDE SHOWN)

NOTES:

1. CONNECTOR ENVELOPE DIMENSION. OTHER COMPONENTS PLACED ON PCB SHALL AVOID THIS ZONE.
2. COPPER THICKNESS MAY NOT VARY MORE THAN 0.02 [.001] WITHIN ANY VIA.
3. CONTACT SAMTEC FOR CONNECTOR PRESS FIT INSTRUCTIONS AND REQUIRED FIXTURES.
4. MINIMUM BOARD THICKNESS: 1.10 [.043].
5. REFER TO SAMTEC XCode® HD PRODUCT SPECIFICATION.
6. NO SURFACE TRACES IN KEEP-OUT ZONE.

TIN (IMMERSION)	Cu	0.025-0.050 [.0010-.0020]
	Sn	0.001-0.002 [.00004-.00008]

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